

ZXMP6A17G

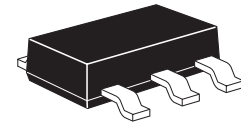
60V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS} = -60V$; $R_{DS(on)} = 0.125\Omega$; $I_D = -4.1A$

DESCRIPTION

This new generation of trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



SOT223

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- SOT223 package

APPLICATIONS

- DC-DC converters
- Power management functions
- Relay and solenoid driving
- Motor control

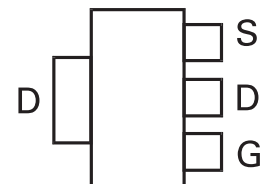
ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMP6A17GTA	7"	12mm	1000 units
ZXMP6A17GTC	13"	12mm	4000 units

DEVICE MARKING

- ZXMP
6A17

PINOUT



Top View

ZXMP6A17G

ABSOLUTE MAXIMUM RATING

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($V_{GS} = -10V$; $T_A = 25^\circ C$) ^(b) ($V_{GS} = -10V$; $T_A = 70^\circ C$) ^(b) ($V_{GS} = -10V$; $T_A = 25^\circ C$) ^(a)	I_D	-4.1 -3.3 -3.0	A
Pulsed Drain Current ^(c)	I_{DM}	-13.7	A
Continuous Source Current (Body Diode) ^(b)	I_S	-4.8	A
Pulsed Source Current (Body Diode) ^(c)	I_{SM}	-13.7	A
Power Dissipation at $T_A = 25^\circ C$ ^(a) Linear Derating Factor	P_D	2.0 16	W mW/ $^\circ C$
Power Dissipation at $T_A = 25^\circ C$ ^(b) Linear Derating Factor	P_D	3.9 31	W mW/ $^\circ C$
Operating and Storage Temperature Range	$T_j: T_{stg}$	-55 to +150	$^\circ C$

THERMAL RESISTANCE

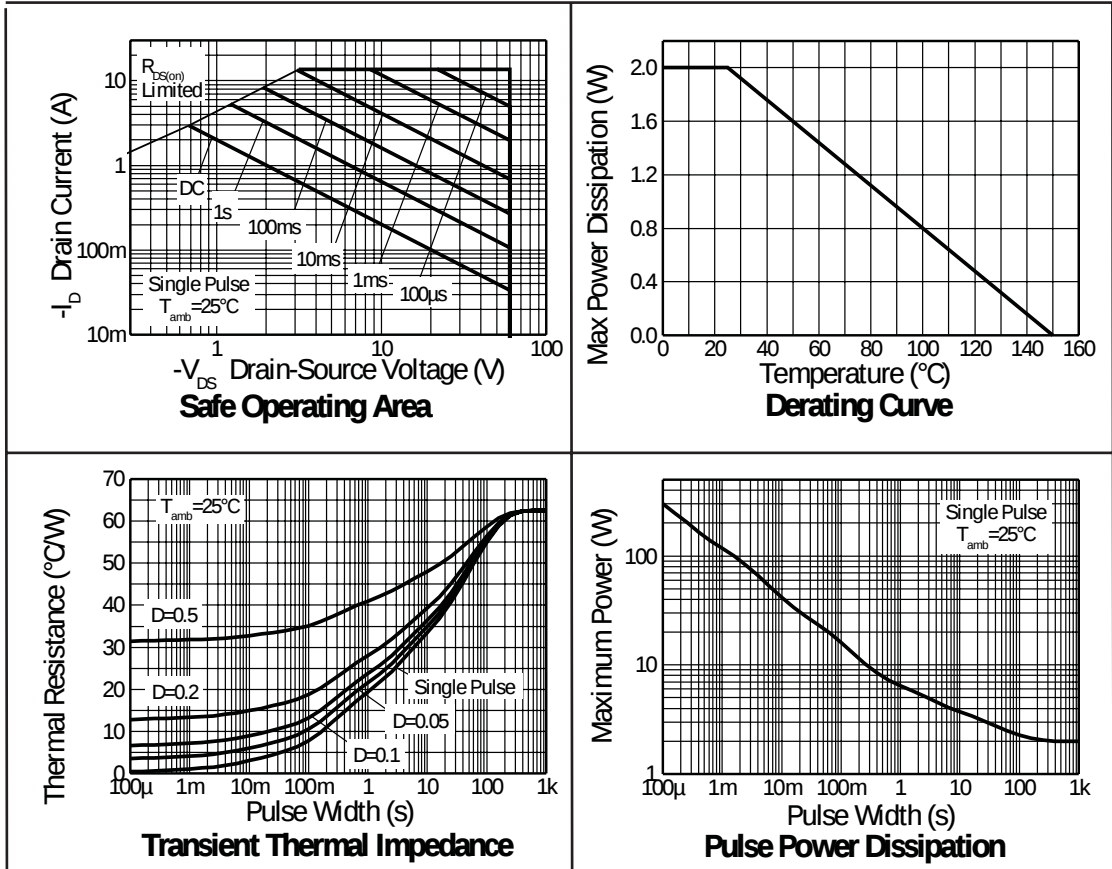
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient ^(a)	$R_{\theta JA}$	62.5	$^\circ C/W$
Junction to Ambient ^(b)	$R_{\theta JA}$	32.2	$^\circ C/W$

NOTES

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
- (b) For a device surface mounted on FR4 PCB measured at $t \leq 10$ secs.
- (c) Repetitive rating 25mm x 25mm FR4 PCB, D=0.05 pulse width limited by maximum junction temperature.

ZXMP6A17G

CHARACTERISTICS



ZXMP6A17G

ELECTRICAL CHARACTERISTICS (at $T_A = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	-60			V	I _D =-250μA, V _{GS} =0V
Zero Gate Voltage Drain Current	I _{DSS}			-1	μA	V _{DS} =-60V, V _{GS} =0V
Gate-Body Leakage	I _{GSS}			100	nA	V _{GS} =±20V, V _{DS} =0V
Gate-Source Threshold Voltage	V _{GS(th)}	-1.0			V	I _D =-250μA, V _{DS} = V _{GS}
Static Drain-Source On-State Resistance ⁽¹⁾	R _{DS(on)}			0.125 0.190	Ω Ω	V _{GS} =-10V, I _D =-2.2A V _{GS} =-4.5V, I _D =-1.8A
Forward Transconductance ⁽¹⁾⁽³⁾	g _{fs}		4.7		S	V _{DS} =-15V,I _D =-2.2A
DYNAMIC ⁽³⁾						
Input Capacitance	C _{iss}		637		pF	V _{DS} =-30V, V _{GS} =0V, f=1MHz
Output Capacitance	C _{oss}		70		pF	
Reverse Transfer Capacitance	C _{rss}		53		pF	
SWITCHING ^{(2) (3)}						
Turn-On Delay Time	t _{d(on)}		2.6		ns	V _{DD} =-30V, I _D =-1A R _G 6.0Ω, V _{GS} =-10V
Rise Time	t _r		3.4		ns	
Turn-Off Delay Time	t _{d(off)}		26.2		ns	
Fall Time	t _f		11.3		ns	
Gate Charge	Q _g		9.8		nC	V _{DS} =-30V,V _{GS} =-5V, I _D =-2.2A
Total Gate Charge	Q _g		17.7		nC	V _{DS} =-30V,V _{GS} =-10V, I _D =-2.2A
Gate-Source Charge	Q _{gs}		1.6		nC	
Gate-Drain Charge	Q _{gd}		4.4		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage ⁽¹⁾	V _{SD}		-0.85	-0.95	V	T _J =25°C, I _S =-2A, V _{GS} =0V
Reverse Recovery Time ⁽³⁾	t _{rr}		25.1		ns	T _J =25°C, I _F =-1.7A, di/dt= 100A/μs
Reverse Recovery Charge ⁽³⁾	Q _{rr}		27.2		nC	

NOTES

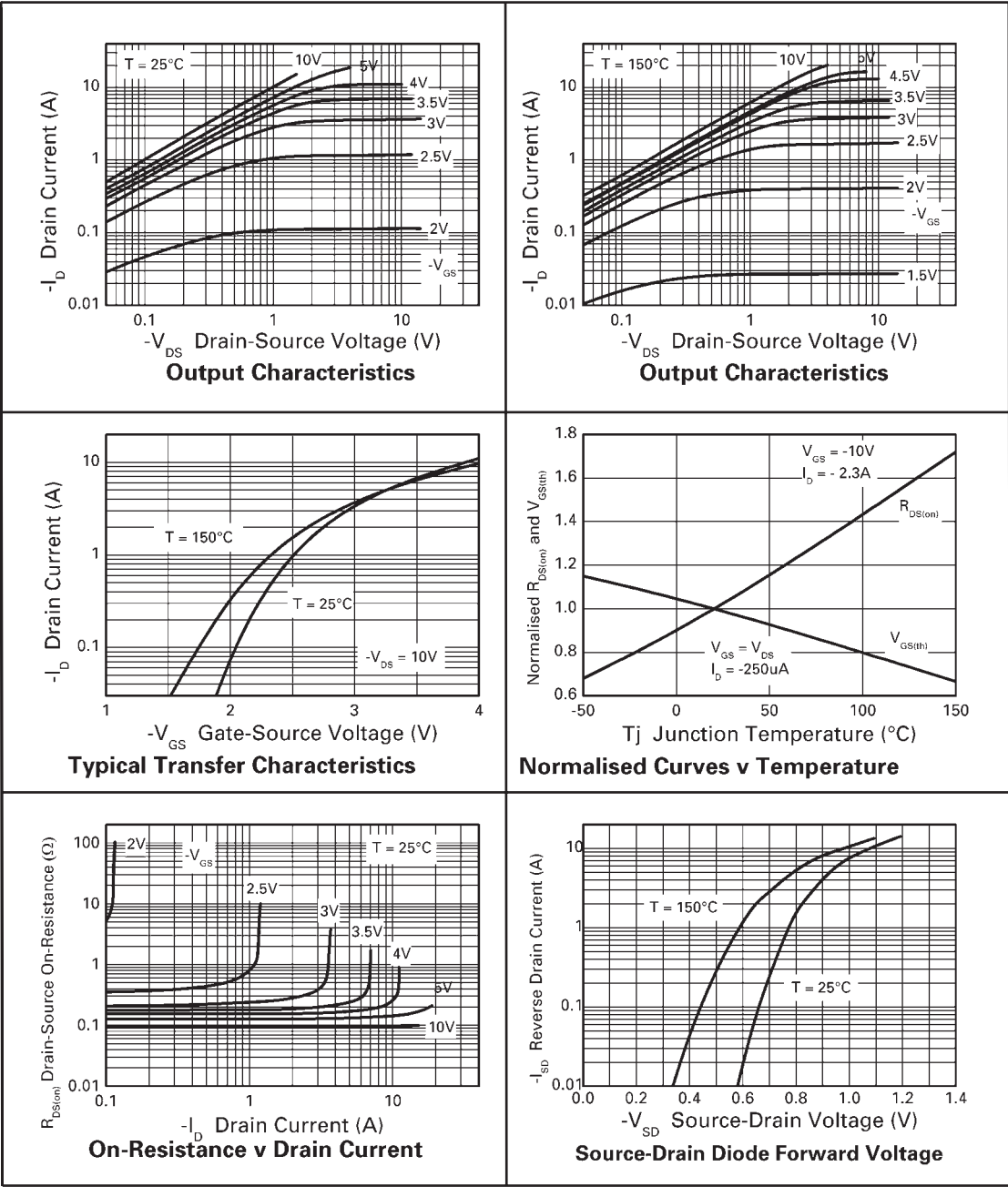
(1) Measured under pulsed conditions. Width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

(2) Switching characteristics are independent of operating junction temperature.

(3) For design aid only, not subject to production testing.

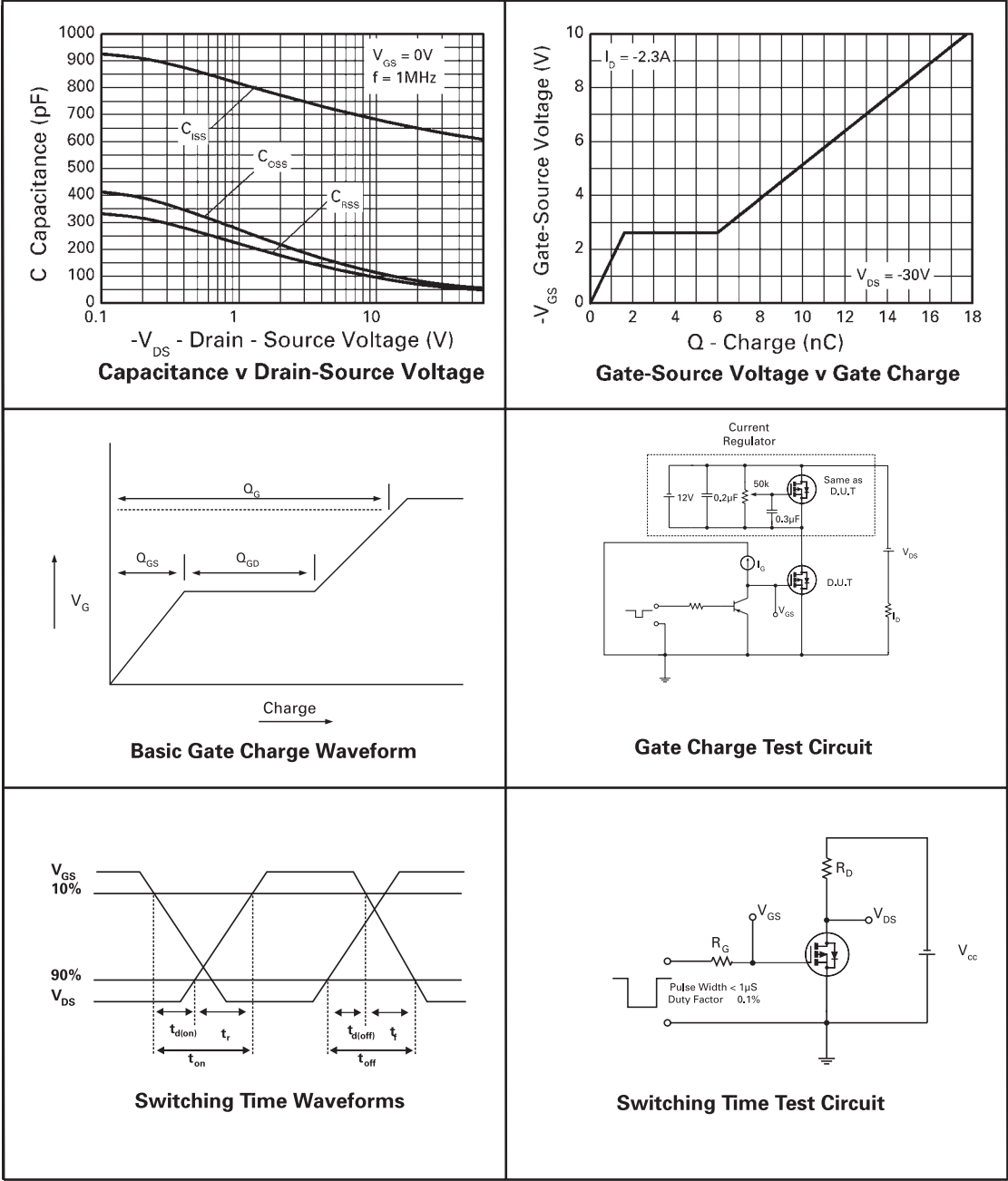
ZXMP6A17G

TYPICAL CHARACTERISTICS



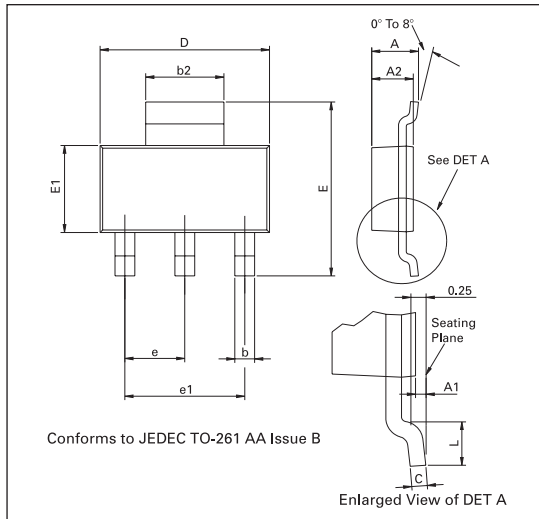
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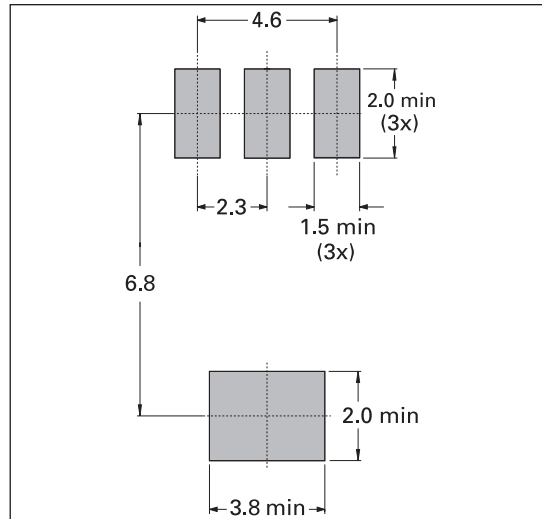


ZXMP6A17G

PACKAGE OUTLINE



PAD LAYOUT DETAILS



PACKAGE DIMENSIONS

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	-	1.80	-	0.071	e	2.30 BSC		0.0905 BSC	
A1	0.02	0.10	0.0008	0.004	e1	4.60 BSC		0.181 BSC	
b	0.66	0.84	0.026	0.033	E	6.70	7.30	0.264	0.287
b2	2.90	3.10	0.114	0.122	E1	3.30	3.70	0.130	0.146
C	0.23	0.33	0.009	0.013	L	0.90	-	0.355	-
D	6.30	6.70	0.248	0.264	-	-	-	-	-

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